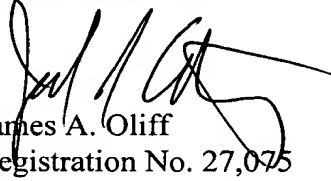


The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. 1.121(c)(ii)).

Respectfully submitted,


James A. Oliff
Registration No. 27,075

Joel S. Armstrong
Registration No. 36,430

JAO:JSA/zmc
Attached: APPENDIX
Date: May 24, 2001

OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

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APPENDIX

Changes to Specification:

The following is a marked-up version of the amended paragraph:

Page 6, line 1-3:

(15) In this semiconductor device, the interconnect substrate ~~as defined in any one of claims 1 to 10~~ may be used as the substrate.

Changes to Claims:

The following are marked-up versions of the amended claims:

10. (Amended) The interconnect substrate as defined in claim 7~~4~~, wherein a plurality of holes are formed in the end parts.

11. (Amended) The interconnect substrate as defined in claim 1~~any one of claims 1 to 10~~, wherein the second portion continuously extends from the first portion.

12. (Amended) The interconnect substrate as defined in claim 1~~any one of claims 1 to 10~~, wherein the second portion is separated from the first portion; and wherein the first and second portions are connected by the interconnect pattern.

16. (Amended) A circuit board over which is mounted the semiconductor device as defined in claim ~~13 or 14~~.

17. (Amended) An electronic instrument provided with the semiconductor device as defined in claim ~~13 or 14~~.

18. (Amended) A method of fabricating a semiconductor device, comprising the steps of: mounting at least one semiconductor chip over the interconnect substrate as defined in claim 1~~any one of claims 1 to 10~~; and superposing the second portion on the first portion of the interconnect substrate.

19. (Amended) A method of inspecting a semiconductor device, comprising the steps of: positioning the semiconductor device as defined in claim 13 ~~or 14~~ by using a plurality of end parts as positioning references; and inspecting electrical characteristics of the semiconductor device.

20. (Amended) A method of mounting a semiconductor device comprising the steps of: positioning the semiconductor device as defined in claim 13 ~~or 14~~ by using a plurality of end parts as positioning references; and mounting the semiconductor device on a circuit board.

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